



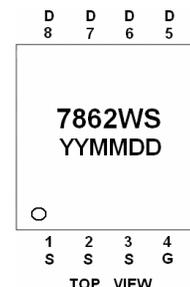
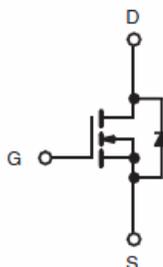
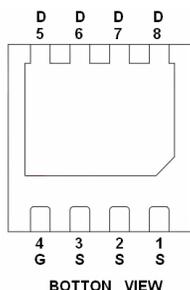
## General Description

AFN7862WS, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge. These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

## Features

- 60V/ 8.7A,  $R_{DS(ON)}=15m\Omega@V_{GS}=10V$
- 60V/ 7.3A,  $R_{DS(ON)}=17m\Omega@V_{GS}=4.5V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- DFN3X3-8L package design

## Pin Description ( DFN3X3-8L )



## Application

- Primary Side Switch
- Synchronous Rectification
- DC/DC Converters & DC/AC Inverters
- Boost Converters

## Pin Define

Pin	Symbol	Description
1~3	S	Source
4	G	Gate
5~8	D	Drain

## Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFN7862WSFN338RG	7862WS	DFN3X3-8L	Tape & Reel	5000 EA

- ※ YY year code
- ※ MM month code
- ※ DD date code
- ※ AFN7862WSFN338RG : 13" Tape & Reel ; Pb- Free ; Halogen -Free



### Absolute Maximum Ratings

( $T_A=25^\circ\text{C}$  Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	$V_{DSS}$	60	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current( $T_J=150^\circ\text{C}$ )	$I_D$	$T_A=25^\circ\text{C}$	11
		$T_A=70^\circ\text{C}$	8
Pulsed Drain Current	$I_{DM}$	90	A
Continuous Source Current(Diode Conduction)	$I_S$	3.2	A
Power Dissipation	$P_D$	$T_A=25^\circ\text{C}$	3.8
		$T_A=70^\circ\text{C}$	2
Operating Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55/150	$^\circ\text{C}$
Thermal Resistance-Junction to Ambient	$t \leq 10 \text{ s}$	$R_{\theta JA}$	26
Thermal Resistance-Junction to Case	Steady-State	$R_{\theta JC}$	1.9

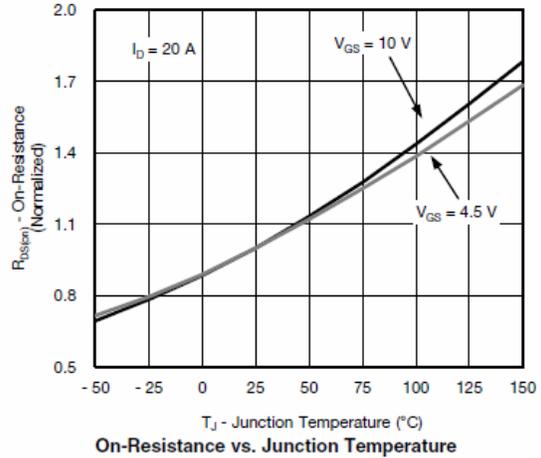
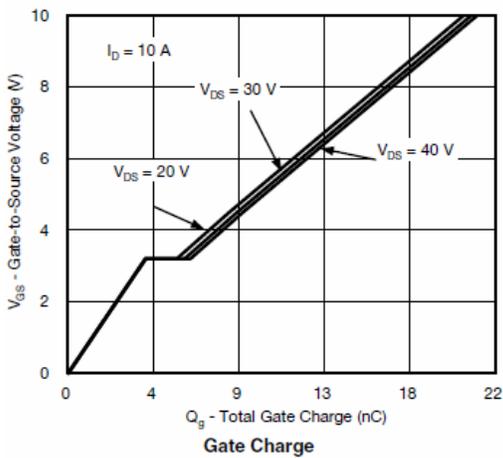
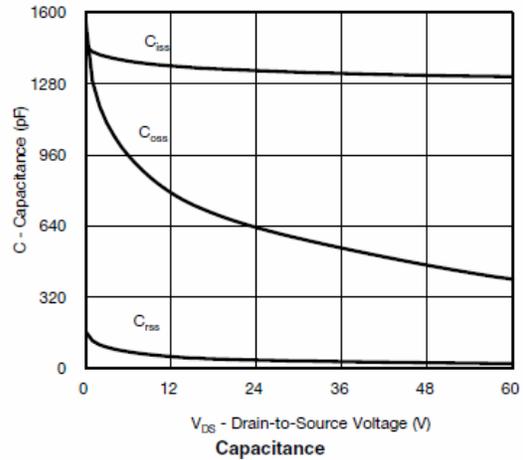
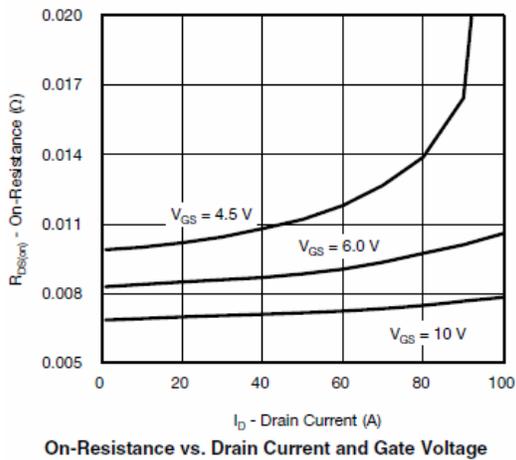
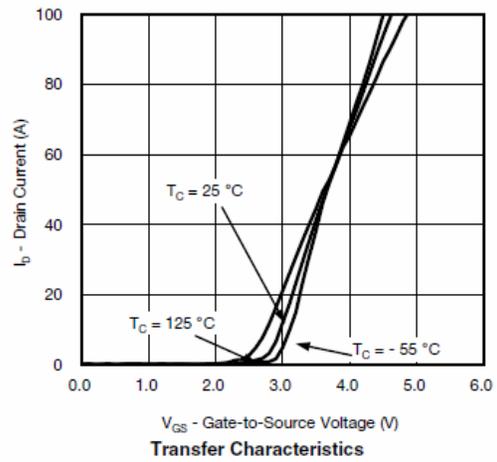
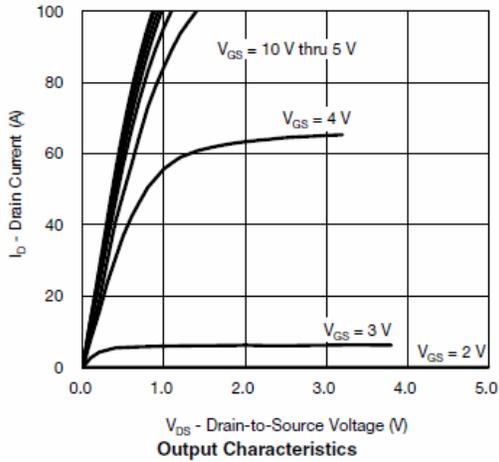
### Electrical Characteristics

( $T_A=25^\circ\text{C}$  Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu\text{A}$	60			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0		2.0	
Gate Leakage Current	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 20V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=48V, V_{GS}=0V$			1	uA
		$V_{DS}=48V, V_{GS}=0V$ $T_J=85^\circ\text{C}$			5	
On-State Drain Current	$I_{D(on)}$	$V_{DS} \geq 5V, V_{GS}=10V$	20			A
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=8.7A$		12	15	m $\Omega$
		$V_{GS}=4.5V, I_D=7.3A$		14	17	
Forward Transconductance	$g_{FS}$	$V_{DS}=5V, I_D=10A$		24		S
Diode Forward Voltage	$V_{SD}$	$I_S=2.0A, V_{GS}=0V$		0.85	1.3	V
<b>Dynamic</b>						
Total Gate Charge	$Q_g$	$V_{DS}=30V, V_{GS}=4.5V$ $I_D \equiv 10A$		10	20	nC
Gate-Source Charge	$Q_{gs}$			5		
Gate-Drain Charge	$Q_{gd}$			4		
Input Capacitance	$C_{iss}$	$V_{DS}=30V, V_{GS}=0V$ $f=1\text{MHz}$		1350		pF
Output Capacitance	$C_{oss}$			450		
Reverse Transfer Capacitance	$C_{rss}$			40		
Turn-On Time	$t_{d(on)}$	$V_{DD}=30V, R_L=3\Omega$ $I_D \equiv 10A, V_{GEN}=10V$ $R_G=1\Omega$		25	50	ns
	$t_r$			100	200	
Turn-Off Time	$t_{d(off)}$			25	50	
	$t_f$			10	20	

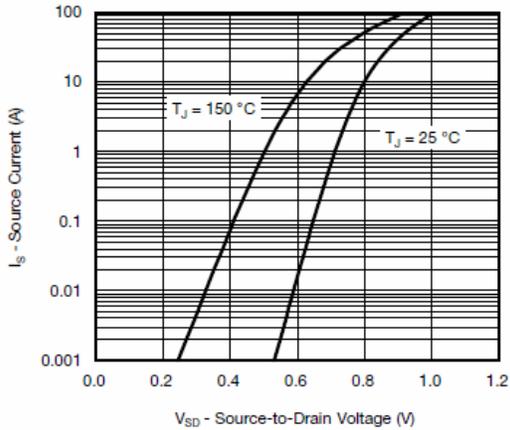


## Typical Characteristics

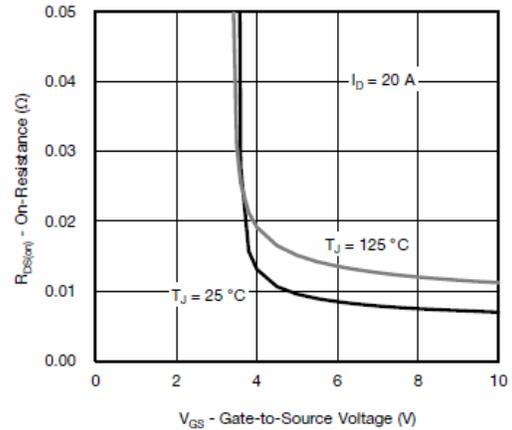




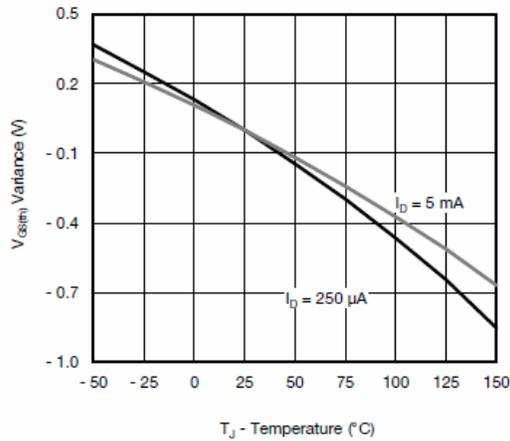
## Typical Characteristics



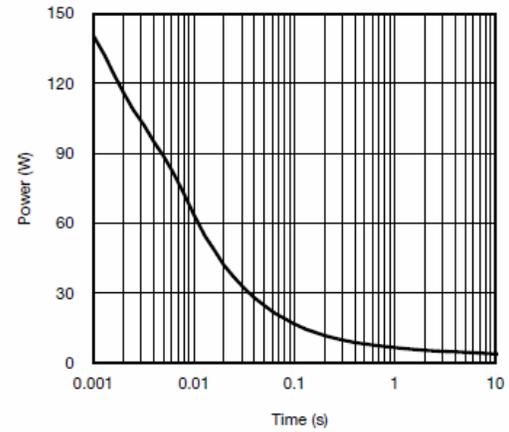
Source-Drain Diode Forward Voltage



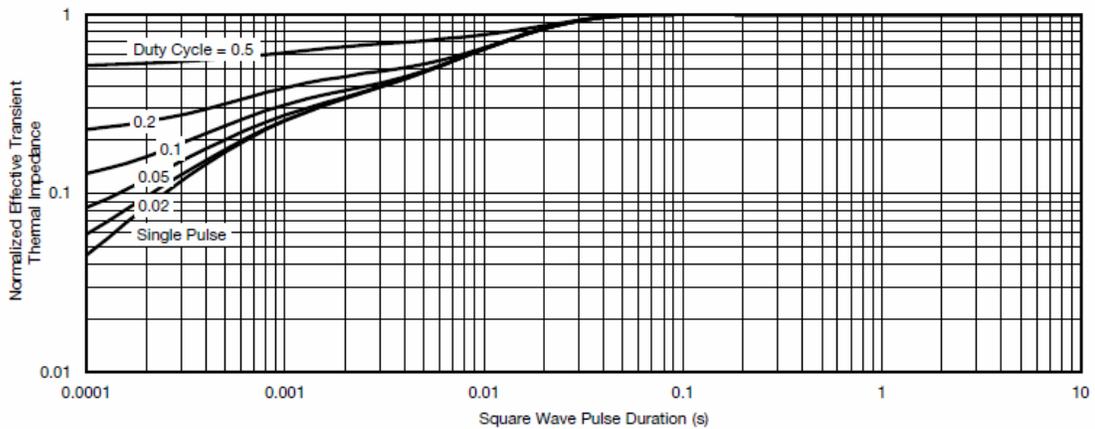
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient

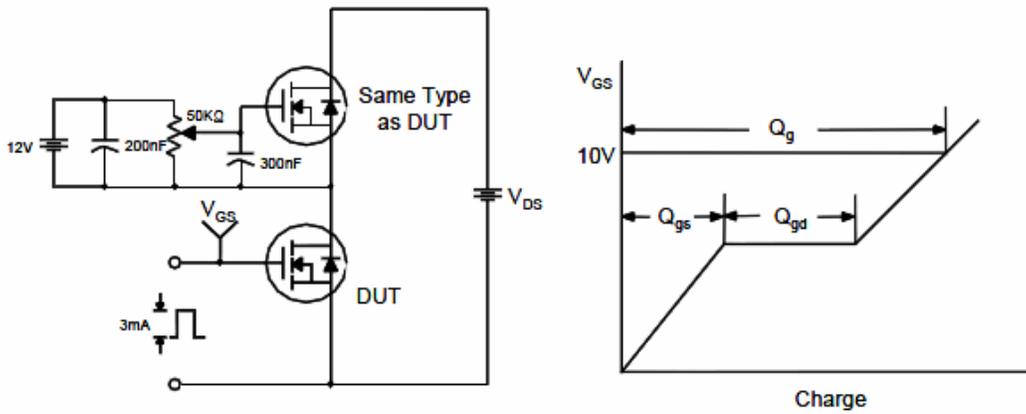


Normalized Thermal Transient Impedance, Junction-to-Case

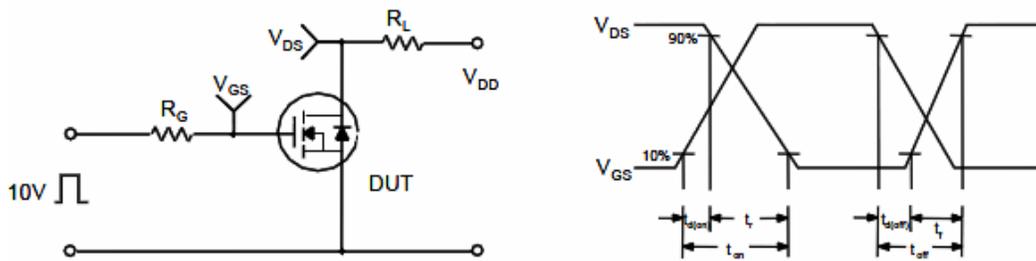


Typical Characteristics

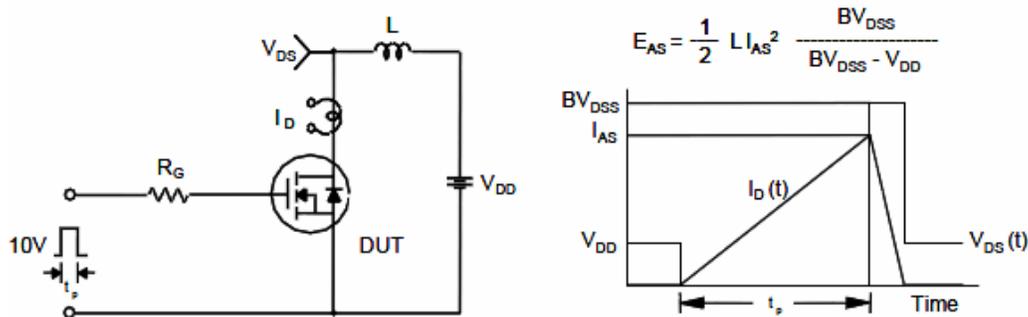
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

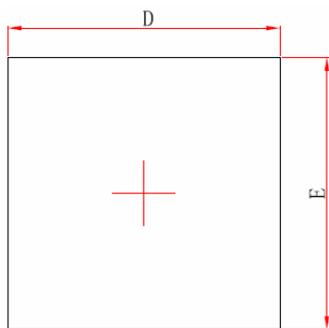


Unclamped Inductive Switching Test Circuit & Waveforms

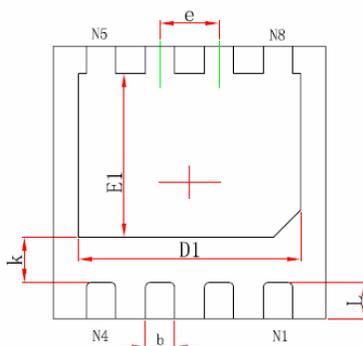




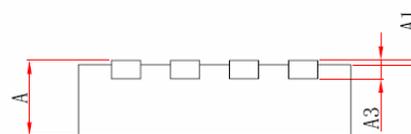
**Package Information ( DFN3X3-8L )**



**Top View**



**Bottom View**



**Side View**

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.800	0.900	0.031	0.035
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	2.924	3.076	0.115	0.121
E	2.924	3.076	0.115	0.121
D1	2.350	2.550	0.093	0.100
E1	1.700	1.900	0.067	0.075
k	0.450	0.550	0.018	0.022
b	0.270	0.370	0.011	0.015
e	0.650TYP.		0.026TYP.	
L	0.324	0.476	0.013	0.019

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